

**IN THE CLAIMS:**

1. Cancelled.

2. Cancelled.

3. Cancelled.

4. Cancelled.

5. Cancelled.

6. Cancelled.

7. Cancelled.

8. (THRICE AMENDED) The A printed circuit board unit comprising:

a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so

as to fix the electronic component to the printed circuit board; and

an interposer disposed between the printed circuit board and the electronic component so as to define a through hole for containing the solder bump wherein

at least an inner surface of the through hole is covered with a coating wet to a melted state of the solder bump, said coating being spaced from an outer periphery of the solder bump.

- 9. Cancelled.
- 10. Withdrawn.
- 11. Withdrawn.
- 12. Withdrawn.
- 13. Withdrawn.
- 14. Withdrawn.
- 15. Withdrawn.
- 16. Cancelled.

17. (NEW) The printed circuit board unit according to claim 8, wherein said interposer is spaced from at least one of the printed circuit board and the electronic component